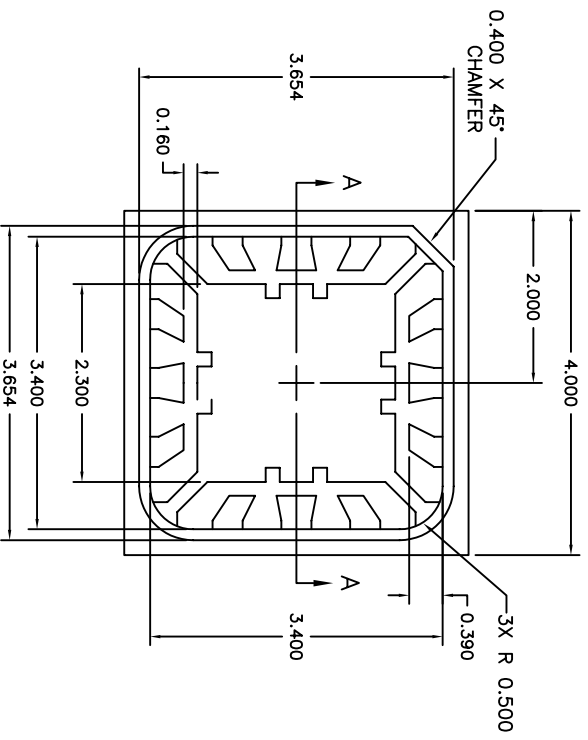


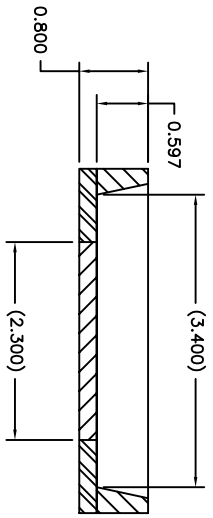
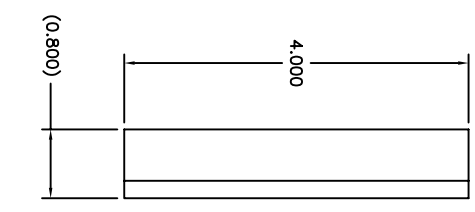
2

1

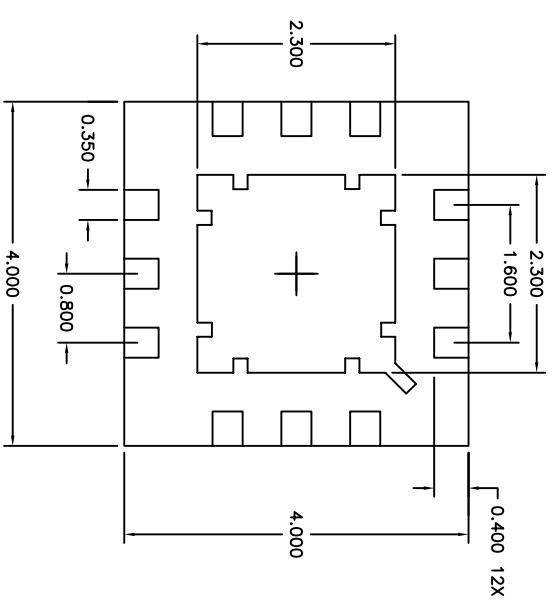
REVISIONS			APPROVED
CON. NO.	DATE	DESCRIPTION	
10474	10/17/05	PRODUCTION RELEASE	D.BENAVANDO



TOP VIEW



SECTION A-A



BOTTOM VIEW

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. FRAME THICKNESS: 0.2030 ±.0076.
 5. DIE PAD: 2.300mm X 2.300mm.
 6. JEDEC OUTLINE: MO-220 (YGG8)



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS

TOLERANCES ARE: XXXX ±.015

ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	W. GRIFFITTS	DATE	10/17/05
APP BY	P. FLASKERUD	DATE	10/17/05
CUSTOMER	---		

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12 Lead 4.00mm x 4.00mm
 MLP Open-Pak

SIZE	PART NO.	REV
A	MLP4X4-12-OP-01	1
SCALE NONE	CAD FILE	SHEET 1 OF 1
	MLP4X4-12-OP-01-R1.DWG	

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